

iC-HG EVAL HG21M preliminary

HIGH-SPEED MODULE FOR SMD VCSEL ARRAYS

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ORDERING INFORMATION

Type	Package	Options	Order Designation
iC-HG	HG21M (DIL28)	-	iC-HG iCSY HG21M

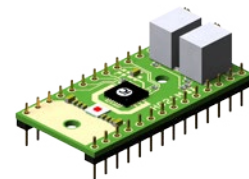


Figure 1: HG21M Package (DIL28)

PIN CONFIGURATION

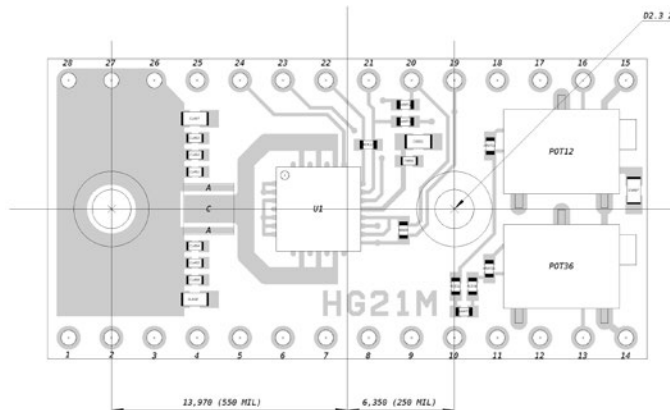


Figure 2: Top view / Dimensions in mm

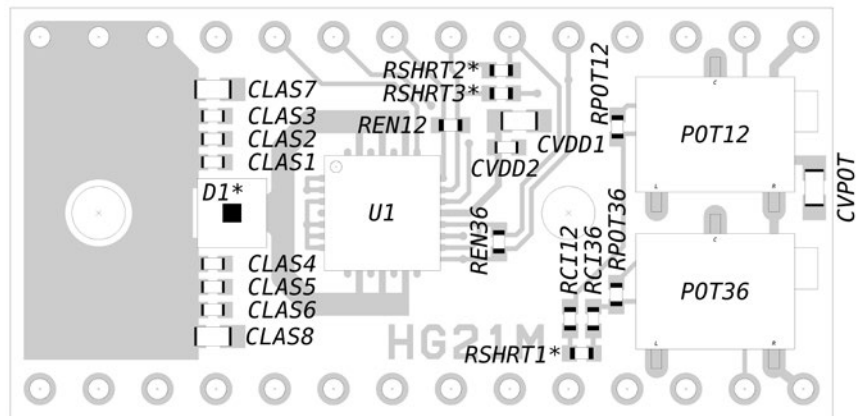
No	Name	Function	No	Name	Function
1	GND	Ground, Analog Ground	15	POTVDD	Potentiometer 12 36 VDD
2	GND	Ground, Analog Ground	16	RC12	Current Control Voltage 12
3	GND	Ground, Analog Ground	17	POTGND	Potentiometer 12 36 GND
4	GND	Ground, Analog Ground	18	POTGND	Potentiometer 12 36 GND
5	nc	not connected	19	EN46	Input Channel 4 + 6
6	nc	not connected	20	EN35	Input Channel 3 + 5
7	nc	not connected	21	EN2	Input Channel 2
8	nc	not connected	22	EN1	Input Channel 1
9	nc	not connected	23	ELVDS	TTL/LVDS Input Selector
10	nc	not connected	24	NER	Error Monitor Output
11	nc	not connected	25	VDD	Supply Voltage
12	nc	not connected	26	LDA	Anode Laser Diode
13	RCI36	Current Control Voltage 36	27	LDA	Anode Laser Diode
14	POTVDD	Potentiometer 12 36 VDD	28	LDA	Anode Laser Diode

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SMD POSITIONS



* Devices are not assembled

Figure 3: SMD Positions

NOTE: Module must be baked (min. 24 h at 100 °C) before exposing to high temperature processes (e.g. reflow soldering) to avoid delamination, PCB/VIA damages, and popcorning.

The PCB has a very low thermal resistance that makes manual soldering of SMT devices difficult.

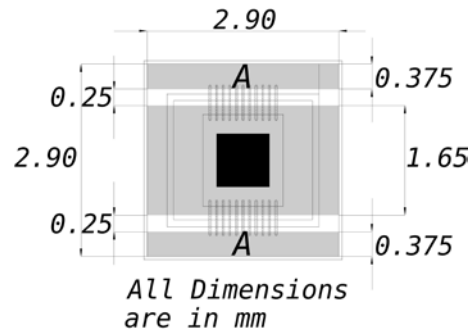


Figure 4: Details of the VCSEL pad

ABSOLUTE MAXIMUM RATINGS

Item No.	Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
TG1	Ta	Operating Ambient Temperature Range		-20		85	°C
TG2	Ts	Storage Temperature Range		-20		85	°C

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SCHEMATICS

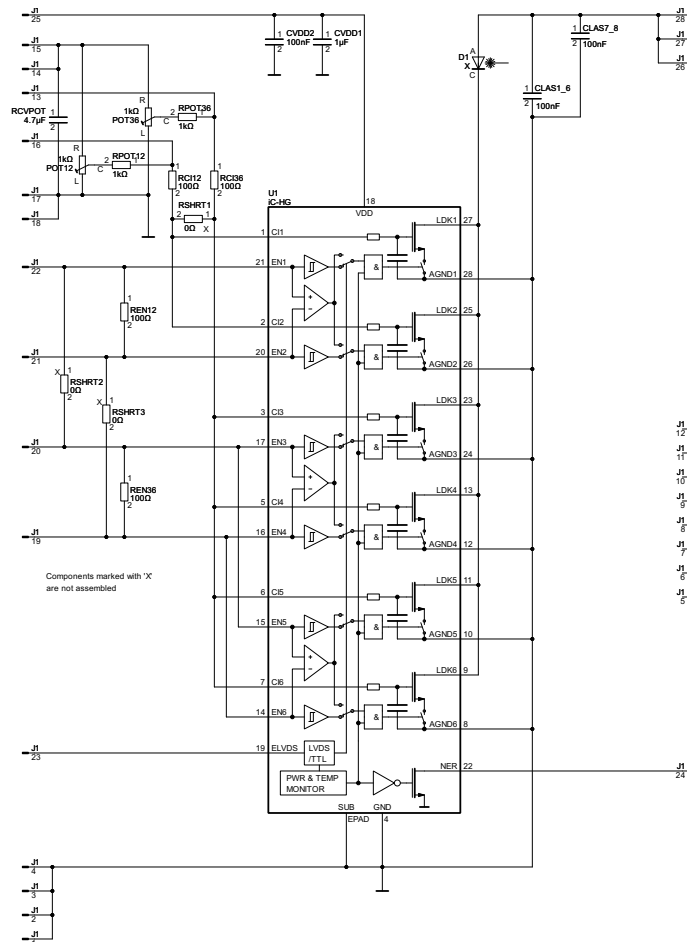


Figure 5: Circuit diagram

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